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B
E. Willis
6-6-01

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of: **Kazuhisa TSUNOI et al.**

Serial Number: **Not Yet Assigned**

Group Art Unit: **Not Yet Assigned**

Filed: **February 8, 2001**

Examiner: **Not Yet Assigned**

For: **MOUNTING METHOD OF SEMICONDUCTOR DEVICE**

PRELIMINARY AMENDMENT

Director of Patents and Trademarks
Washington, D.C. 20231

March 14, 2001

Sir:

Prior to Examination of the merits, please amend the above-mentioned application as follows:

IN THE CLAIMS:

✓
Add new claims 6 - 11 as follows:

6. A structure comprising:
a semiconductor device having bumps;
a board having pads so that each of the bumps is joined to a corresponding one of the pads,
each of the pads having a deformed portion with which a corresponding one of the bumps contact;
and
an insulating adhesive provided between the semiconductor device and the board, wherein
contraction of the insulating adhesive maintains joints of the bumps and the pads, said joints

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